

# DATA SHEET

# NEC

## NPN SILICON RF TRANSISTOR

# 2SC5015

### NPN EPITAXIAL SILICON RF TRANSISTOR FOR HIGH-FREQUENCY LOW-NOISE AMPLIFICATION 4-PIN SUPER MINIMOLD (18)

#### FEATURES

- High fr:  $f_T = 12$  GHz TYP. @  $V_{CE} = 3$  V,  $I_C = 10$  mA,  $f = 2$  GHz
- Low noise and high gain
- Low voltage operation
- 4-pin super minimold (18) package

#### ★ ORDERING INFORMATION

Part Number	Quantity	Supplying Form
2SC5015	50 pcs (Non reel)	<ul style="list-style-type: none"> <li>• 8 mm wide embossed taping</li> <li>• Pin 3 (Base), Pin 4 (Emitter) face the perforation side of the tape</li> </ul>
2SC5015-T1	3 kpcs/reel	

**Remark** To order evaluation samples, contact your nearby sales office.  
The unit sample quantity is 50 pcs.

#### ABSOLUTE MAXIMUM RATINGS ( $T_A = +25^\circ\text{C}$ )

Parameter	Symbol	Ratings	Unit
Collector to Base Voltage	$V_{CBO}$	9	V
Collector to Emitter Voltage	$V_{CEO}$	6	V
Emitter to Base Voltage	$V_{EBO}$	2	V
Collector Current	$I_C$	30	mA
Total Power Dissipation	$P_{tot}$	150	mW
Junction Temperature	$T_j$	150	$^\circ\text{C}$
Storage Temperature	$T_{stg}$	-65 to +150	$^\circ\text{C}$

**Caution** Observe precautions when handling because these devices are sensitive to electrostatic discharge.

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Not all devices/types available in every country. Please check with local NEC Compound Semiconductor Devices representative for availability and additional information.

**ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = +25°C)**

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
DC Characteristics						
Collector Cut-off Current	I <sub>CBO</sub>	V <sub>CB</sub> = 5 V, I <sub>E</sub> = 0 mA	–	–	0.1	μA
Emitter Cut-off Current	I <sub>EBO</sub>	V <sub>EB</sub> = 1 V, I <sub>C</sub> = 0 mA	–	–	0.1	μA
DC Current Gain	h <sub>FE</sub> <sup>Note 1</sup>	V <sub>CE</sub> = 3 V, I <sub>C</sub> = 10 mA	75	–	150	–
RF Characteristics						
Gain Bandwidth Product	f <sub>T</sub>	V <sub>CE</sub> = 3 V, I <sub>C</sub> = 10 mA, f = 2 GHz	–	12	–	GHz
Insertion Power Gain	S <sub>21e</sub>   <sup>2</sup>	V <sub>CE</sub> = 3 V, I <sub>C</sub> = 10 mA, f = 2 GHz	9	11	–	dB
Noise Figure	NF	V <sub>CE</sub> = 3 V, I <sub>C</sub> = 3 mA, f = 2 GHz	–	1.5	2.5	dB
Reverse Transfer Capacitance	C <sub>re</sub> <sup>Note 2</sup>	V <sub>CB</sub> = 3 V, I <sub>E</sub> = 0 mA, f = 1 MHz	–	0.3	0.5	pF

**Notes 1.** Pulse measurement: PW ≤ 350 μs, Duty Cycle ≤ 2%

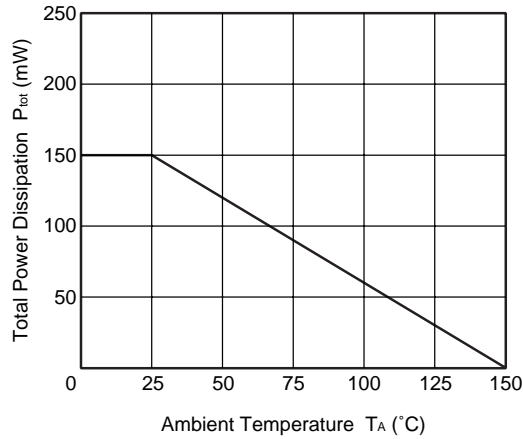
**2.** Collector to base capacitance when the emitter grounded

**h<sub>FE</sub> CLASSIFICATION**

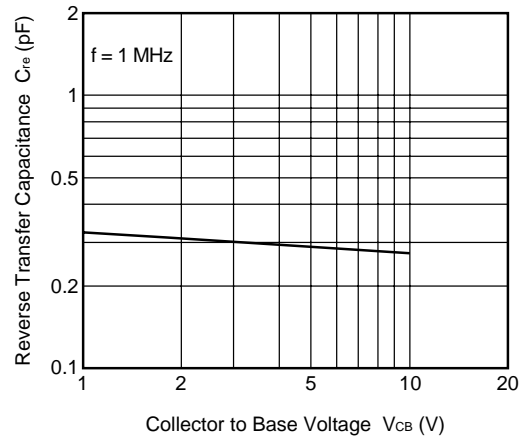
Rank	KB
Marking	T83
h <sub>FE</sub> Value	75 to 150

★ TYPICAL CHARACTERISTICS (T<sub>A</sub> = +25°C, unless otherwise specified)

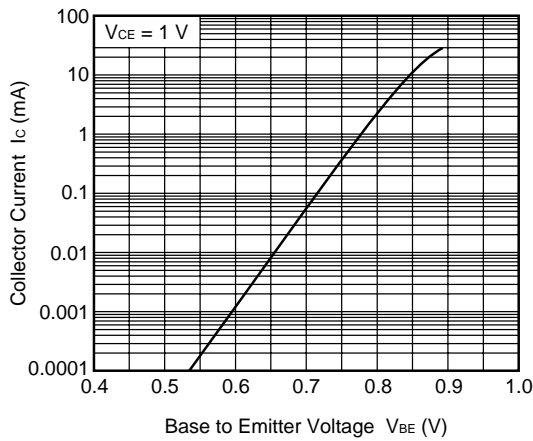
TOTAL POWER DISSIPATION vs. AMBIENT TEMPERATURE



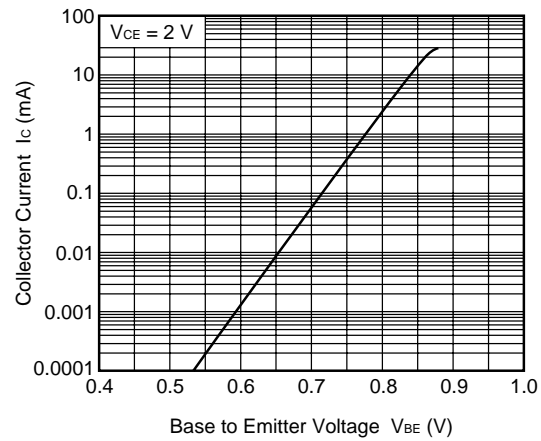
REVERSE TRANSFER CAPACITANCE vs. COLLECTOR TO BASE VOLTAGE



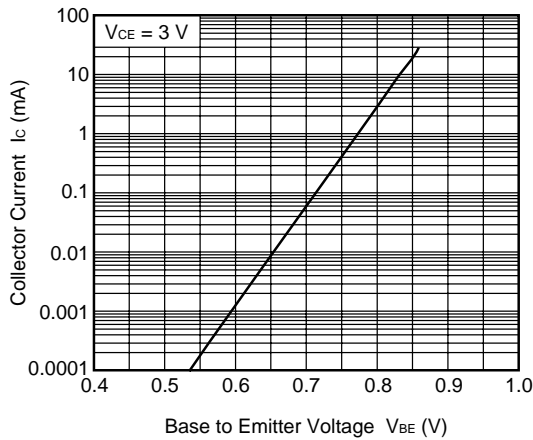
COLLECTOR CURRENT vs. BASE TO EMITTER VOLTAGE



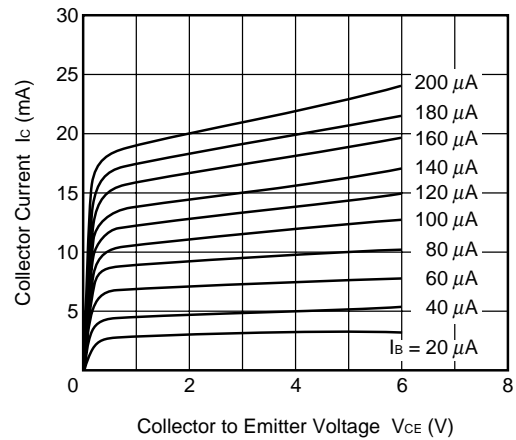
COLLECTOR CURRENT vs. BASE TO EMITTER VOLTAGE



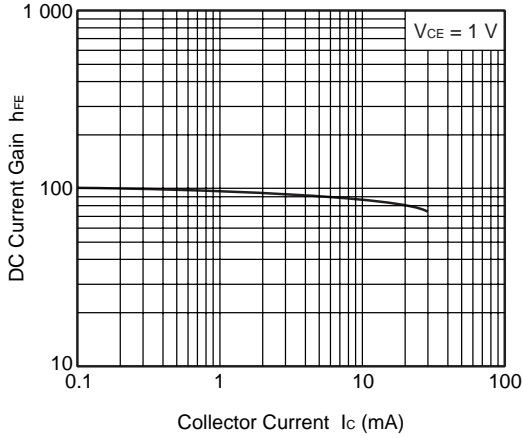
COLLECTOR CURRENT vs. BASE TO EMITTER VOLTAGE



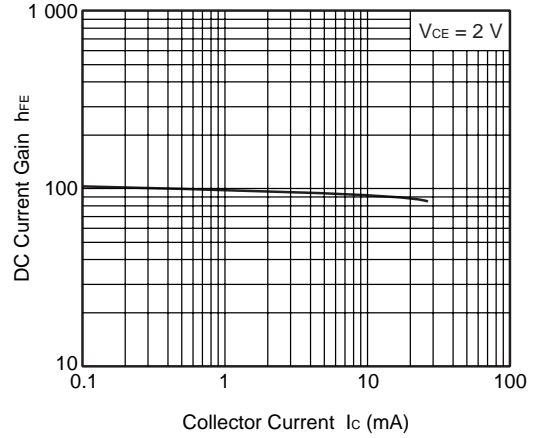
COLLECTOR CURRENT vs. COLLECTOR TO EMITTER VOLTAGE



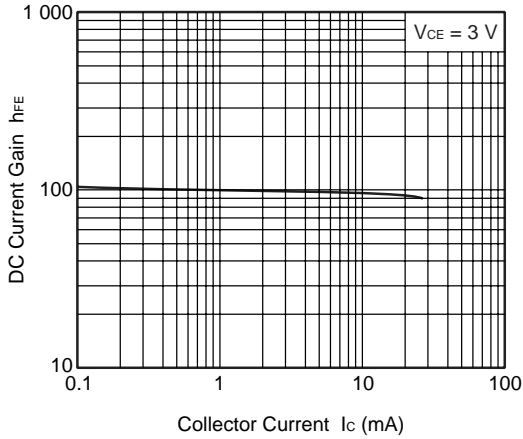
DC CURRENT GAIN vs. COLLECTOR CURRENT



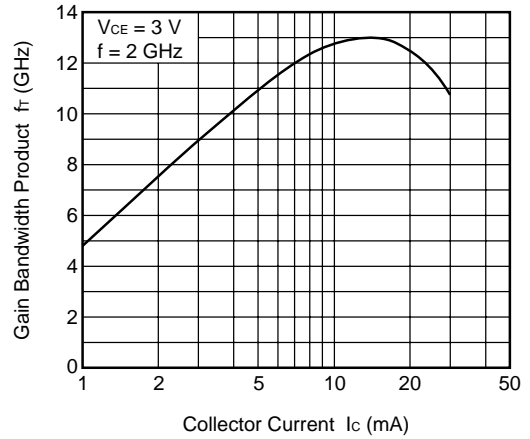
DC CURRENT GAIN vs. COLLECTOR CURRENT



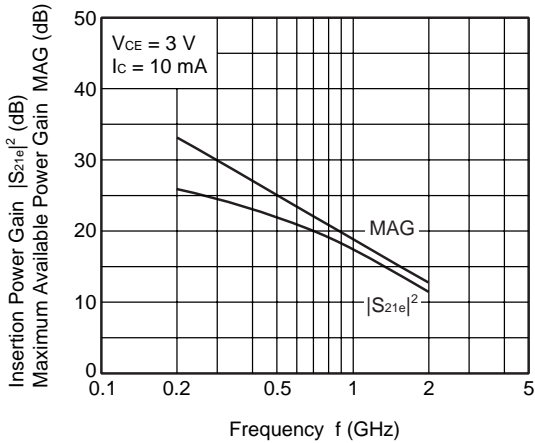
DC CURRENT GAIN vs. COLLECTOR CURRENT



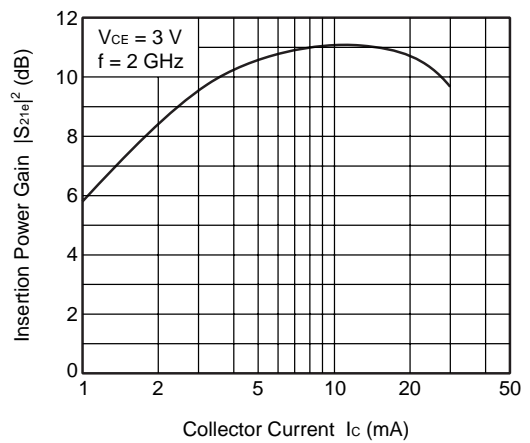
GAIN BANDWIDTH PRODUCT vs. COLLECTOR CURRENT

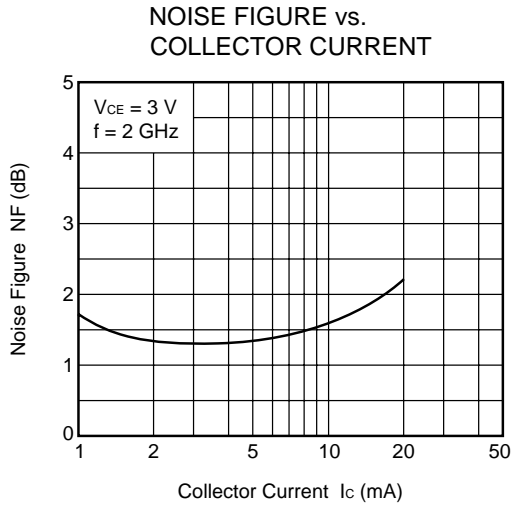


INSERTION POWER GAIN, MAG vs. FREQUENCY



INSERTION POWER GAIN vs. COLLECTOR CURRENT





**Remark** The graphs indicate nominal characteristics.

**S-PARAMETERS**

S-parameters/Noise parameters are provided on the NEC Compound Semiconductor Devices Web site in a form (S2P) that enables direct import to a microwave circuit simulator without keyboard input.

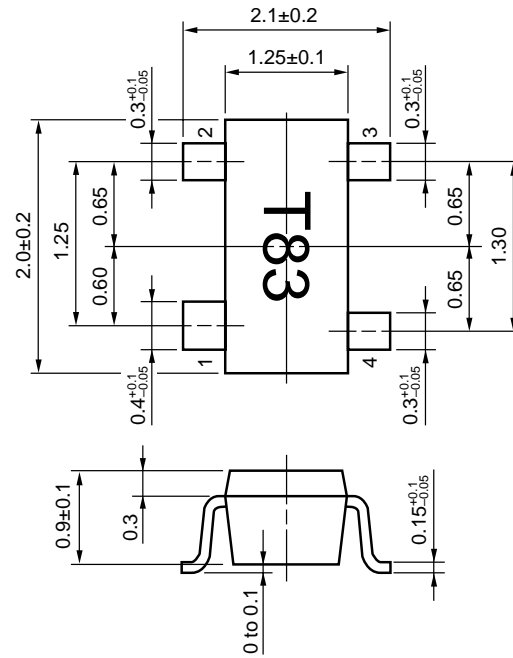
Click here to download S-parameters.

[RF and Microwave] → [Device Parameters]

URL <http://www.csd-nec.com/>

PACKAGE DIMENSIONS

4-PIN SUPER MINIMOLD (18) (UNIT: mm)



PIN CONNECTIONS

- 1. Collector
- 2. Emitter
- 3. Base
- 4. Emitter

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